

Global Molding Equipment for Wafer and Panel Level Packaging Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

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Abstracts

According to our (Global Info Research) latest study, the global Molding Equipment for Wafer and Panel Level Packaging market size was valued at US\$ 418 million in 2025 and is forecast to a readjusted size of US\$ 668 million by 2032 with a CAGR of 7.0% during review period.

In 2024, global Molding Equipment for Wafer and Panel Level Packaging production reached approximately 387 units, with an average global market price of around US\$ 974,250 per unit.

Molding Equipment for Wafer and Panel Level Packaging is core semiconductor advanced packaging equipment used for encapsulating wafers or large-size panels. It applies molding compounds (epoxy resins, etc.) to the surface of wafers/panels through precision molding processes such as transfer molding or compression molding, forming a uniform protective layer that integrates multiple chips. Featuring high molding precision, excellent encapsulation uniformity, and compatibility with large-size substrates, it effectively protects chips from environmental interference, enhances mechanical stability and electrical performance, and is critical for realizing heterogeneous integration and 3D stacking in advanced packaging technologies (e.g., fan-out wafer/panel level packaging).

The single-line production capacity of Molding Equipment for Wafer and Panel Level Packaging is 39 to 42 units per year, the average gross profit margin was 45.2%.

The cost structure of Molding Equipment for Wafer and Panel Level Packaging is dominated by four core components with clear weights: core component costs account

for the largest share at 45%-55%, mainly including precision molding modules, high-precision motion control systems, temperature/pressure control units, and die-casting mechanisms, where the accuracy and stability of core components directly determine the equipment's process capability and cost level. R&D and certification costs make up 25%-30%, dedicated to optimizing molding process parameters, improving compatibility with large-size panels and special molding compounds, and meeting SEMI semiconductor industry standards, as high technological barriers and strict reliability verification are key to market entry. Production and assembly costs represent 15%-20%, covering precision machining, system integration, and long-term stability testing?high-precision assembly and process calibration for large-size substrates increase manufacturing complexity. Packaging and logistics costs constitute the remaining 5%-8%, including shockproof packaging, professional transportation, and on-site installation and commissioning services, with high requirements for equipment transportation safety and technical support.

The industry chain of Molding Equipment for Wafer and Panel Level Packaging consists of three interconnected tiers: upstream includes suppliers of core components (motion control systems, precision molds, temperature/pressure sensors), raw materials (epoxy molding compounds), precision mechanical parts, and electronic components, as well as providers of process software and testing instruments. Midstream involves enterprises engaged in product design, core component integration, system assembly, and performance calibration, focusing on adjusting equipment specifications and process parameters to adapt to different wafer/panel sizes and advanced packaging process requirements (e.g., 3D stacking, heterogeneous integration). Downstream covers semiconductor wafer fabs, advanced packaging and testing enterprises (OSAT), and IDM manufacturers, with demand driven by the upgrading of semiconductor advanced packaging technologies and the expansion of applications in high-performance computing, AI, and automotive electronics.

Demand for Molding Equipment for Wafer and Panel Level Packaging is growing rapidly driven by the global expansion of advanced packaging markets, the widespread adoption of wafer/panel level packaging technologies, and the surge in demand for high-performance chips in AI, 5G, and intelligent driving. It addresses pain points such as low efficiency and poor uniformity of traditional packaging equipment in large-size substrate processing, while the accelerated domestic substitution trend in semiconductor equipment provides broad market space. Key business opportunities lie in developing high-precision equipment for large-size panel level packaging to meet mass production needs, optimizing compatibility with third-generation semiconductor materials and new molding compounds, and expanding into emerging semiconductor manufacturing hubs.

Additionally, strengthening independent R&D of core technologies to break foreign monopolies and collaborating with downstream enterprises for customized process solutions can further tap into the high-growth potential of the advanced packaging equipment market.

This report is a detailed and comprehensive analysis for global Molding Equipment for Wafer and Panel Level Packaging market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Molding Method and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Molding Equipment for Wafer and Panel Level Packaging market size and forecasts, in consumption value (\$ Million), sales quantity (Units), and average selling prices (US\$/Unit), 2021-2032

Global Molding Equipment for Wafer and Panel Level Packaging market size and forecasts by region and country, in consumption value (\$ Million), sales quantity (Units), and average selling prices (US\$/Unit), 2021-2032

Global Molding Equipment for Wafer and Panel Level Packaging market size and forecasts, by Molding Method and by Application, in consumption value (\$ Million), sales quantity (Units), and average selling prices (US\$/Unit), 2021-2032

Global Molding Equipment for Wafer and Panel Level Packaging market shares of main players, shipments in revenue (\$ Million), sales quantity (Units), and ASP (US\$/Unit), 2021-2026

The Primary Objectives in This Report Are:

To determine the size of the total market opportunity of global and key countries

To assess the growth potential for Molding Equipment for Wafer and Panel Level Packaging

To forecast future growth in each product and end-use market

To assess competitive factors affecting the marketplace

This report profiles key players in the global Molding Equipment for Wafer and Panel Level Packaging market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Towa, Besi, ASMPT, APIC YAMADA (Yamaha Robotics), Shanghai Xinsheng, Tongling Trinity Technology, I-PEX, Kitakami Techno, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Molding Equipment for Wafer and Panel Level Packaging market is split by Molding Method and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Molding Method, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Molding Method

Compression Molding

Transfer Molding

Injection Molding

Vacuum-Assisted Molding

Market segment by Substrate Format

Wafer-Level Molding (200 Mm / 300 Mm)

Panel-Level Molding (Large Panel / Fan-Out Panel)

Strip-Level Molding

Market segment by Automation Level

Semi-Automatic Molding System

Fully Automatic Molding System

Market segment by Application

Semiconductor Packaging

Advanced Packaging For Mobile And Consumer Electronics

Automotive And Industrial Electronics

High-Reliability And IoT Devices

Major players covered

Towa

Besi

ASMPT

APIC YAMADA (Yamaha Robotics)

Shanghai Xinsheng

Tongling Trinity Technology

I-PEX

Kitakami Techno

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Molding Equipment for Wafer and Panel Level Packaging product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Molding Equipment for Wafer and Panel Level Packaging, with price, sales quantity, revenue, and global market share of Molding Equipment for Wafer and Panel Level Packaging from 2021 to 2026.

Chapter 3, the Molding Equipment for Wafer and Panel Level Packaging competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Molding Equipment for Wafer and Panel Level Packaging breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

Chapter 5 and 6, to segment the sales by Molding Method and by Application, with sales market share and growth rate by Molding Method, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with

sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026. and Molding Equipment for Wafer and Panel Level Packaging market forecast, by regions, by Molding Method, and by Application, with sales and revenue, from 2027 to 2032.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Molding Equipment for Wafer and Panel Level Packaging.

Chapter 14 and 15, to describe Molding Equipment for Wafer and Panel Level Packaging sales channel, distributors, customers, research findings and conclusion.

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